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## **NTE2380 (N-Ch) & NTE2381 (P-Ch) Complementary Silicon Gate MOSFETs Enhancement Mode, High Speed Switch TO-220 Type Package**

### **Description:**

The NTE2380 (N-Ch) and NTE2381 (P-Ch) are complementary TMOS power FETs in a TO220 type package designed for high voltage, high speed power switching applications such as switching regulators, converters, solenoid, and relay drivers.

### **Features:**

- Silicon Gate for Fast Switching Speeds
- Rugged – SOA is Power Dissipation Limited
- Source-to-Drain Diode Characterized for Use With Inductive Loads

### **Absolute Maximum Ratings:**

Drain–Source Voltage, $V_{DSS}$ .....	500V
Drain–Gate Voltage ( $R_{GS} = 1M\Omega$ ), $V_{DGR}$ .....	500V
Gate–Source Voltage, $V_{GS}$	
NTE2380 .....	$\pm 20V$
NTE2381 .....	$\pm 30V$
Drain Current, $I_D$	
Continuous	
NTE2380 .....	2.5A
NTE2381 .....	2.7A
Pulsed	
NTE2380 .....	10A
NTE2381 .....	10.8A
Total Power Dissipation ( $T_C = +25^\circ C$ ), $P_D$	
NTE2380 .....	40W
Derate Above $25^\circ C$ .....	$0.32W/^\circ C$
NTE2381 .....	85W
Derate Above $25^\circ C$ .....	$0.68W/^\circ C$
Operating Temperature Range, $T_{opr}$	
NTE2380 .....	$-55^\circ$ to $+150^\circ C$
NTE2381 .....	$-65^\circ$ to $+150^\circ C$
Storage Temperature Range, $T_{stg}$	
NTE2380 .....	$-55^\circ$ to $+150^\circ C$
NTE2381 .....	$-65^\circ$ to $+150^\circ C$
Thermal Resistance, Junction-to-Ambient, $R_{thJA}$ .....	$62.5^\circ C/W$
Thermal Resistance, Junction-to-Case, $R_{thJC}$	
NTE2380 .....	$3.12^\circ C/W$
NTE2381 .....	$2.4^\circ C/W$
Maximum Lead Temperature (During Soldering, 1/8" from case, 5sec), $T_L$ .....	$+300^\circ C$

**Electrical Characteristics:** ( $T_C = +25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF Characteristics</b>						
Drain–Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0, I_D = 0.25\text{mA}$	500	—	—	V
Zero Gate Voltage Drain Current NTE2380 NTE2381 NTE2380 NTE2381	$I_{\text{DSS}}$	$V_{DS} = 500\text{V}, V_{GS} = 0$	—	—	0.25	mA
			—	—	1	$\mu\text{A}$
		$V_{DS} = 400\text{V}, V_{GS} = 0, T_J = +125^\circ\text{C}$	—	—	1.0	mA
			—	—	10	$\mu\text{A}$
Gate–Body Leakage Current, Forward NTE2380 NTE2381	$I_{\text{GSSF}}$	$V_{GSF} = 20\text{V}, V_{DS} = 0$	—	—	500	nA
		$V_{GSF} = 30\text{V}, V_{DS} = 0$	—	—	100	nA
Gate–Body Leakage Current, Reverse NTE2380 NTE2381	$I_{\text{GSSR}}$	$V_{GSF} = 20\text{V}, V_{DS} = 0$	—	—	500	nA
		$V_{GSF} = 30\text{V}, V_{DS} = 0$	—	—	100	nA
<b>ON Characteristics</b> (Note 1)						
Gate Threshold Voltage NTE2380 NTE2381	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 0.25\text{mA}$	2.0	—	4.0	V
			3.0	—	5.0	V
Static Drain–Source On–Resistance NTE2380 NTE2381	$r_{DS(\text{on})}$	$V_{GS} = 10\text{V}, I_D = 1\text{A}$	—	—	3	$\Omega$
		$V_{GS} = 10\text{V}, I_D = 1.35\text{A}$	—	3.9	4.9	$\Omega$
Forward Transconductance NTE2380 NTE2381	$g_{FS}$	$V_{DS} \geq 7.5\text{V}, I_D = 1\text{A}$	1	—	—	mhos
		$V_{DS} = 50\text{V}, I_D = 1.35\text{A}$	—	2.35	—	mhos
<b>Dynamic Characteristics</b>						
Input Capacitance NTE2380 NTE2381	$C_{iss}$	$V_{DS} = 25\text{V}, V_{GS} = 0, f = 1\text{MHz}$	—	—	400	pF
			—	510	660	pF
Output Capacitance NTE2380 NTE2381	$C_{oss}$		—	—	150	pF
			—	70	90	pF
Reverse Transfer Capacitance NTE2380 NTE2381	$C_{rss}$		—	—	40	pF
			—	9.5	12	pF
<b>Switching Characteristics</b> (Note 1)						
Turn–On Time NTE2380 NTE2381	$t_{d(\text{on})}$	$V_{DD} \approx 200\text{V}, I_D = 1\text{A}, R_{\text{gen}} = 50\Omega$	—	—	60	ns
		$V_{DD} = 250\text{V}, I_D = 2.7\text{A}, R_{\text{gen}} = 25\Omega$	—	12	35	ns
Rise Time NTE2380 NTE2381	$t_r$	$V_{DD} \approx 200\text{V}, I_D = 1\text{A}, R_{\text{gen}} = 50\Omega$	—	—	50	ns
		$V_{DD} = 250\text{V}, I_D = 2.7\text{A}, R_{\text{gen}} = 25\Omega$	—	56	120	ns
Turn–Off Time NTE2380 NTE2381	$t_{d(\text{off})}$	$V_{DD} \approx 200\text{V}, I_D = 1\text{A}, R_{\text{gen}} = 50\Omega$	—	—	60	ns
		$V_{DD} = 250\text{V}, I_D = 2.7\text{A}, R_{\text{gen}} = 25\Omega$	—	35	80	ns
Fall Time NTE2380 NTE2381	$t_f$	$V_{DD} \approx 200\text{V}, I_D = 1\text{A}, R_{\text{gen}} = 50\Omega$	—	—	30	ns
		$V_{DD} = 250\text{V}, I_D = 2.7\text{A}, R_{\text{gen}} = 25\Omega$	—	45	100	ns

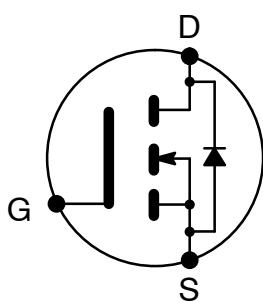
Note 1. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

**Electrical Characteristics (Cont'd):** ( $T_C = +25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit	
<b>Switching Characteristics (Cont'd) (Note 1)</b>							
Total Gate Charge NTE2380	$Q_g$	$V_{GS} = 10\text{V}, V_{DS} = 400\text{V}, I_D = \text{Rated } I_D$	-	12	15	ns	
NTE2381			-	18	23	ns	
Gate-Source Charge NTE2380	$Q_{gs}$		-	6	-	ns	
NTE2381			-	3.6	-	ns	
Gate-Drain Charge NTE2380	$Q_{gd}$		-	6	-	ns	
NTE2381			-	9.2	-	ns	
<b>Source Drain Diode Characteristics (Note 1)</b>							
Forward On-Voltage NTE2380	$V_{SD}$	$I_S = \text{Rated } I_D, V_{GS} = 0$	-	-	1.6	V	
NTE2381			-	-	2.7	V	
Forward Turn-On Time	$t_{on}$	Limited by stray inductance					
Reverse Recovery Time NTE2380	$t_{rr}$		-	500	-	ns	
NTE2381			-	270	-	ns	
<b>Internal Package Inductance</b>							
Internal Drain Inductance	$L_d$	Measured from contact screw on tab to center of die	-	3.5	-	nH	
		Measured from the drain lead 0.25" from package to center of die	-	4.5	-	nH	
Internal Source Inductance	$L_s$	Measured from the source lead 0.25" from package to center of pad	-	7.5	-	nH	

Note 1. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

**NTE2380**



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